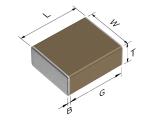
Multilayer Ceramic Chip Capacitors

C7563X7S1H226M230LE

Production		
C7563X7S1H226MT***S		
Commercial Grade		
SoftSoft Termination		
C7563 [EIA 3025]		
Production		
TDK		
ROHS REACH Halogen Free Lead Free		



	Size
Length(L)	7.50mm ±0.50mm
Width(W)	6.30mm ±0.50mm
Thickness(T)	2.50mm Max.
Terminal Width(B)	0.30mm Min.
Recommended Land Pattern (PA)	5.20mm to 5.80mm
Recommended Land Pattern (PB)	1.70mm to 1.90mm
Recommended Land Pattern (PC)	6.40mm to 7.40mm

Electrical Characteristics		
Capacitance	22μF ±20%	
Rated Voltage	50VDC	
Temperature Characteristic	X7S(±22%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	22ΜΩ	

Other		
Operating Temp. Range	-55 to 125°C	
Soldering Method	Reflow	
AEC-Q200	NO	
Packing	Embossed (Plastic)Taping [330mm Reel]	
Package Quantity	1000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

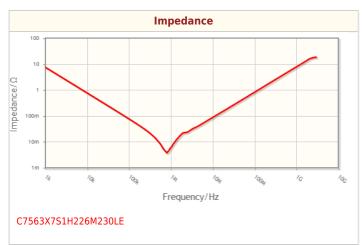
 $^{! \ \}mbox{All specifications}$ are subject to change without notice.

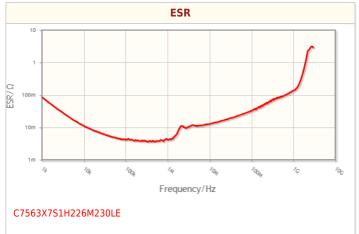


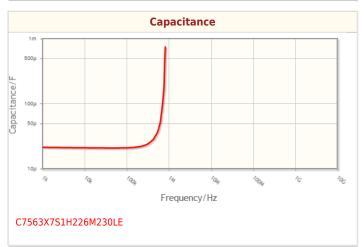
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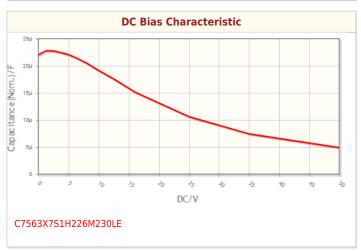
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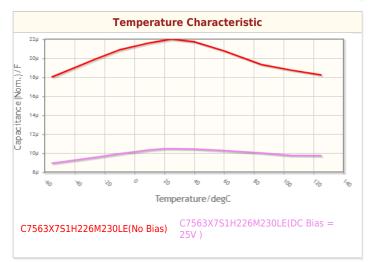
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

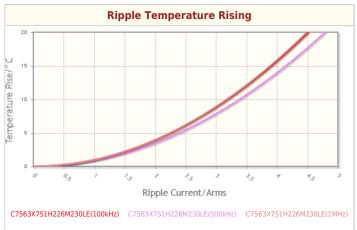












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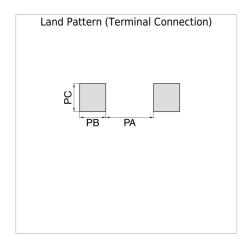
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Multilayer Ceramic Chip Capacitors

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Associated Images



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